



9/B
4-10-03
Mallish
PATENT

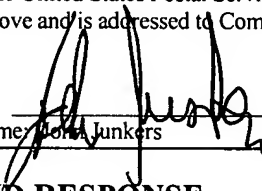
THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: NAKATANI ET AL. Examiner: C. CHU
Serial No.: 10/033,322 Group Art Unit: 2815
Filed: DECEMBER 27, 2001 Docket No.: 10873.860US01
Title: COMPONENT BUILT-IN MODULE AND METHOD FOR PRODUCING
THE SAME

CERTIFICATE UNDER 37 CFR 1.10:

"Express Mail" mailing label number: EV168365381US
Date of Deposit: April 3, 2003

I hereby certify that this correspondence is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to Commissioner for Patents, Washington, D.C. 20231.

By: 
Name: John Junkers

AMENDMENT AND RESPONSE

Commissioner for Patents
Washington, D.C. 20231



Dear Sir:

In response to the Office Action mailed on December 4, 2002, please enter the following amendments and remarks.

In the Specification

Please insert the following new paragraph at page 17, after line 13 as follows:

B1 --Furthermore, in Figure 2, reference numeral 200 denotes a wiring pattern formed on the core layer 205, and 201 denotes a bare semiconductor chip that is an active component mounted on the wiring pattern 200. Furthermore, reference numeral 204 denotes a chip component that is a passive component similarly mounted on the wiring pattern 200, and 202 denotes an electric insulating layer formed of a composite material composed of an inorganic filler and a thermosetting resin. Furthermore, reference numeral 206 denotes an electric insulating layer formed on the core layer 205, and 207 denotes an inner via.--

RECEIVED
MAY -9 2003
TECHNOLOGY CENTER 2800

B